

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XC3202BxxxMR-G

Typical Mass: 15 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	0.415	Silicon	27700	7440-21-3
	-	Arsenic	<1	7440-38-2
Leadframe	5.053	Copper	336900	7440-50-8
	0.013	Tin	800	7440-31-5
	0.011	Zinc	700	7440-66-6
	0.014	Chromium	900	7440-47-3
	0.125	Silver	8300	7440-22-4
Die attach	0.096	Silver	6400	7440-22-4
	0.048	Epoxy	3200	—
Bonding wire	0.037	Gold	2400	7440-57-5
Resin	7.923	Silica	528200	60676-86-0
	0.699	Epoxy resin	46600	—
	0.466	Phenol resin	31100	—
Plating	0.100	Tin	6700	7440-31-5

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."